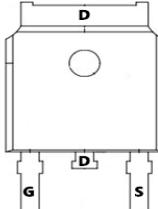
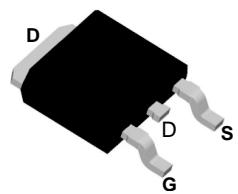
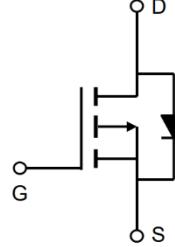




TM30P03D

P -Channel Enhancement Mosfet

General Description <ul style="list-style-type: none"> • Low $R_{DS(ON)}$ • RoHS and Halogen-Free Compliant Applications <ul style="list-style-type: none"> • Load switch • PWM 	General Features <p>$V_{DS} = -30V$ $I_D = -30A$</p> <p>$R_{DS(ON)} = 25\text{ m}\Omega$ (typ.) @ $V_{GS} = -10V$</p> <p>100% UIS Tested 100% R_g Tested</p> 			
	<p style="text-align: center;">D:TO-252-3L</p>  			
Marking: 30P03				
Absolute Maximum Ratings (TC=25°C unless otherwise noted)				
Symbol	Parameter	Rating	Units	
V_{DS}	Drain-Source Voltage	-30	V	
V_{GS}	Gate-Source Voltage	± 20	V	
$I_D @ T_c = 25^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-30	A	
$I_D @ T_c = 100^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-17	A	
I_{DM}	Pulsed Drain Current ²	-110	A	
EAS	Single Pulse Avalanche Energy ³	25	mJ	
I_{AS}	Avalanche Current	-10	A	
$P_D @ T_A = 25^\circ C$	Total Power Dissipation ⁴	4.0	W	
T_{STG}	Storage Temperature Range	-55 to 150	°C	
T_J	Operating Junction Temperature Range	-55 to 150	°C	
Thermal Data				
Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	---	35	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D= -250\mu\text{A}$	-30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}= -30\text{V}$, $V_{GS}=0\text{V}$,	-	-	-1	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0\text{V}$, $V_{GS}= \pm 20\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D= -250\mu\text{A}$	-1.0	-1.5	-2.5	V
$R_{DS(\text{on})}$ note3	Static Drain-Source on-Resistance	$V_{GS}= -10\text{V}$, $I_D= -7\text{A}$	-	25	34	$\text{m}\Omega$
		$V_{GS}= -4.5\text{V}$, $I_D= -4\text{A}$	-	35	45	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}= -15\text{V}$, $V_{GS}=0\text{V}$, $f=1.0\text{MHz}$	-	982	-	pF
C_{oss}	Output Capacitance		-	135	-	pF
C_{rss}	Reverse Transfer Capacitance		-	109	-	pF
Q_g	Total Gate Charge	$V_{DS}= -15\text{V}$, $I_D= -4\text{A}$, $V_{GS}= -10\text{V}$	-	10	-	nC
Q_{gs}	Gate-Source Charge		-	2	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	2.7	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}= -15\text{V}$, $I_D= -7\text{A}$, $V_{GS}= -10\text{V}$, $R_{\text{GEN}}=2.5\Omega$	-	11	-	ns
t_r	Turn-on Rise Time		-	19	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	45	-	ns
t_f	Turn-off Fall Time		-	26	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_s	Maximum Continuous Drain to Source Diode Forward Current	-	-	-30	A	
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	-40	A	
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s= -7\text{A}$	-	-0.8	-1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$

Typical Performance Characteristics

Figure1: Output Characteristics

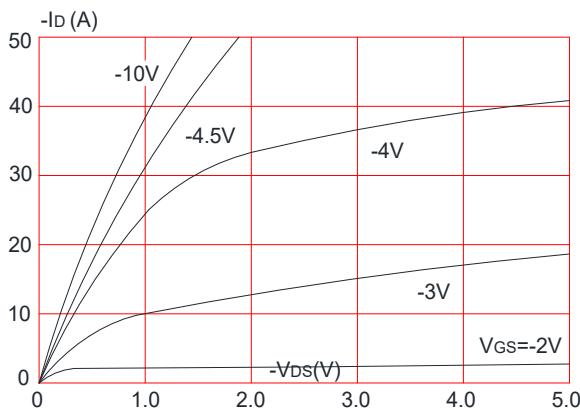


Figure 3: On-resistance vs. Drain Current

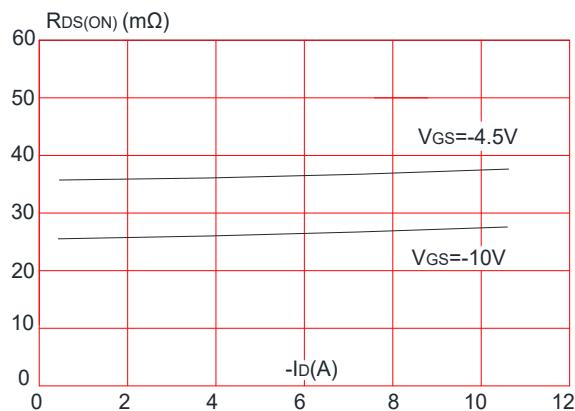


Figure 5: Gate Charge Characteristics

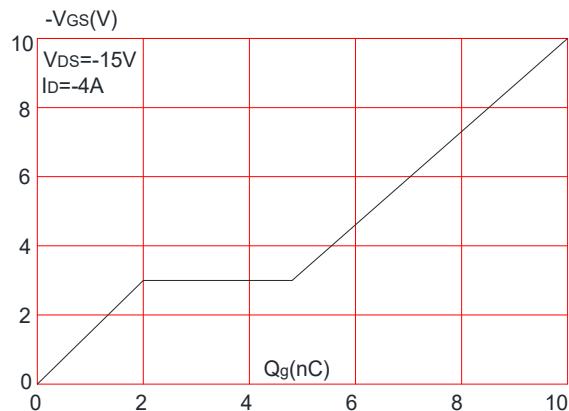


Figure 2: Typical Transfer Characteristics

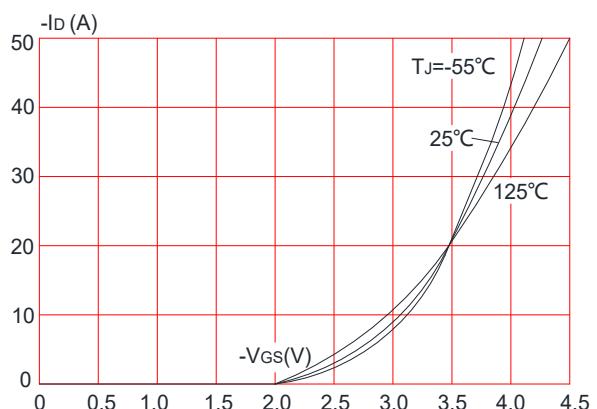


Figure 4: Body Diode Characteristics

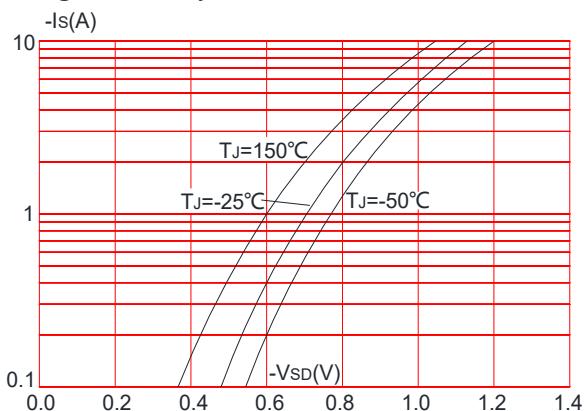


Figure 6: Capacitance Characteristics

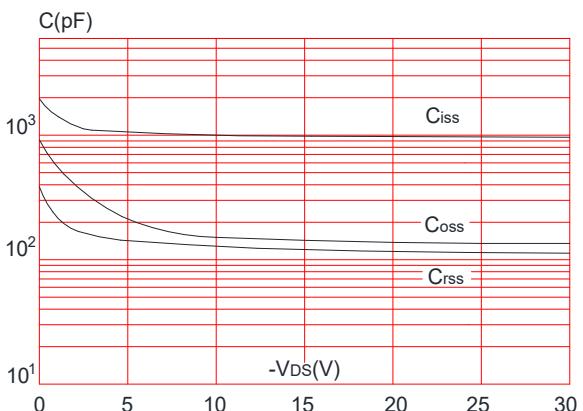


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

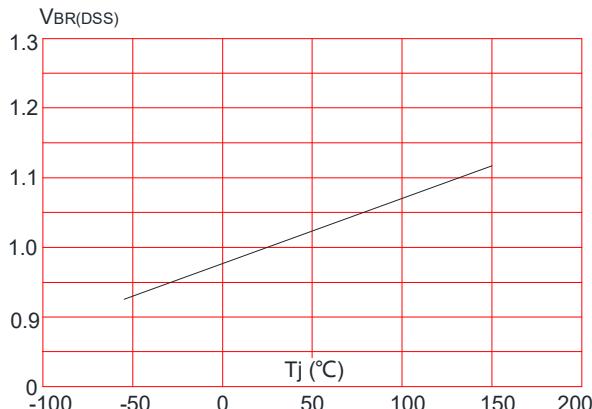


Figure 8: Normalized on Resistance vs. Junction Temperature

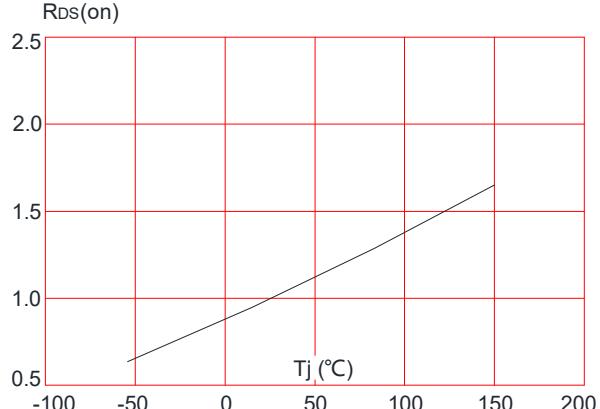


Figure 9: Maximum Safe Operating Area

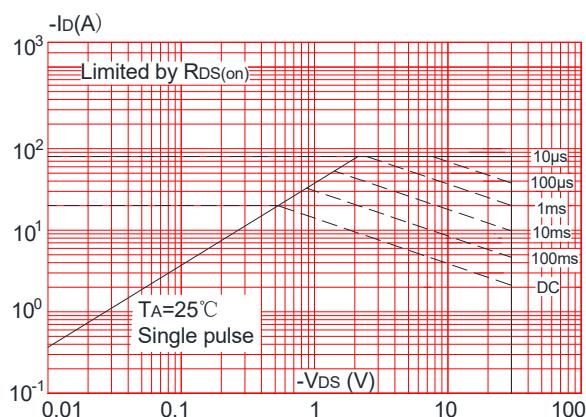


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

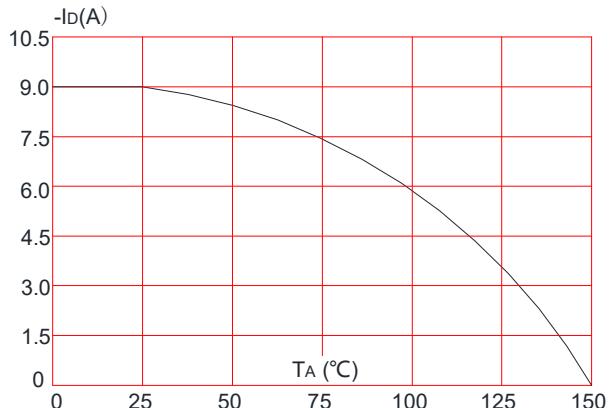
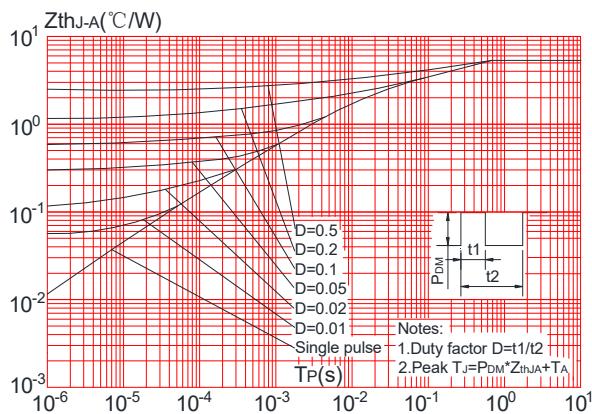
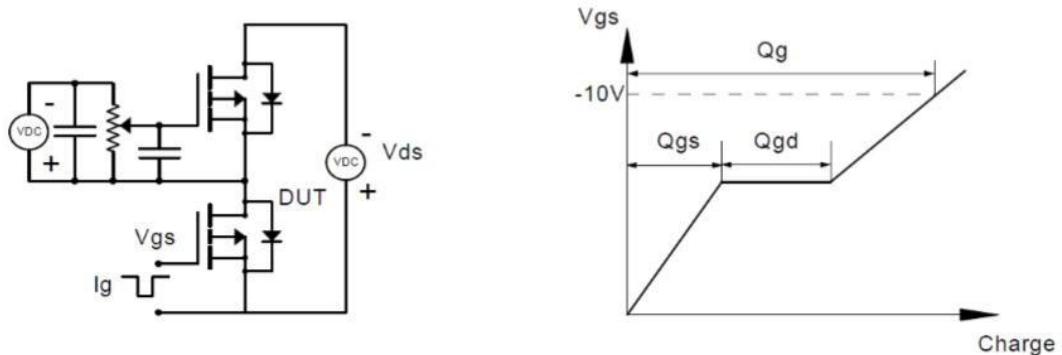


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

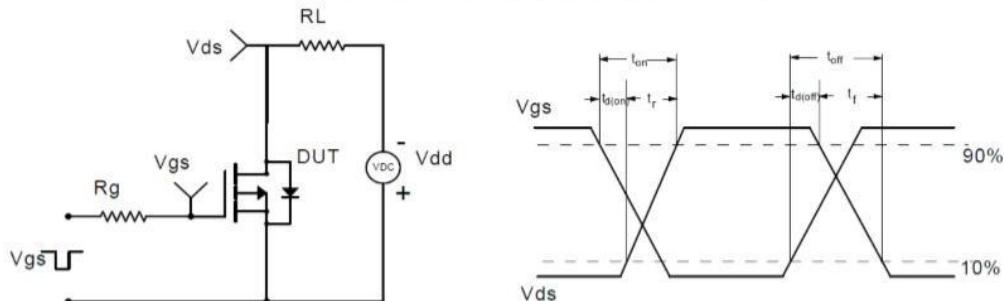


Test Circuit

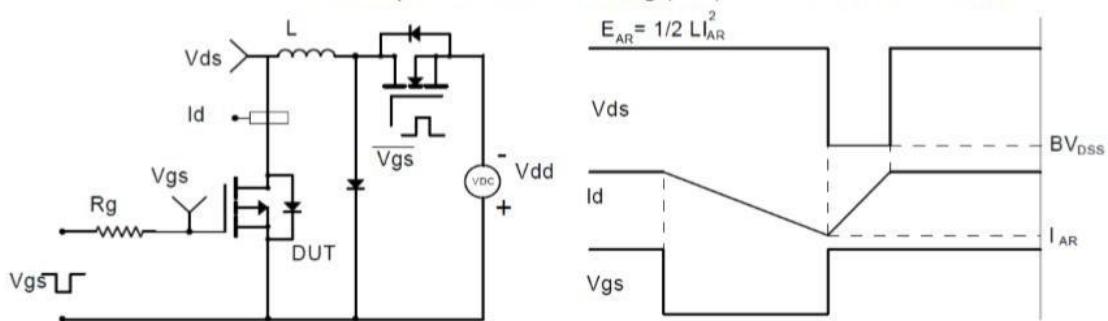
Gate Charge Test Circuit & Waveform



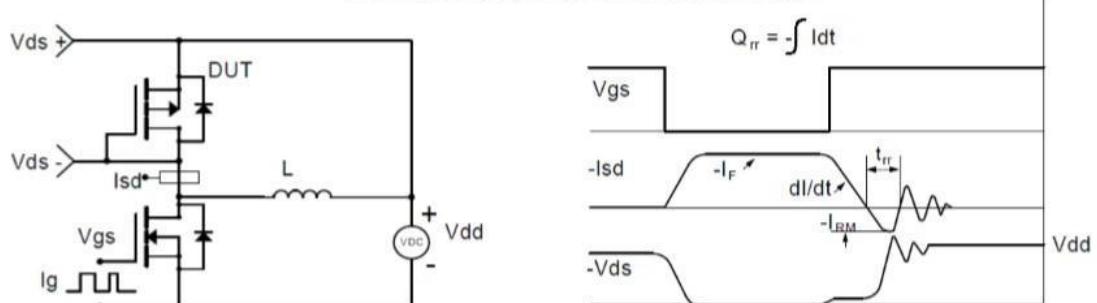
Resistive Switching Test Circuit & Waveforms



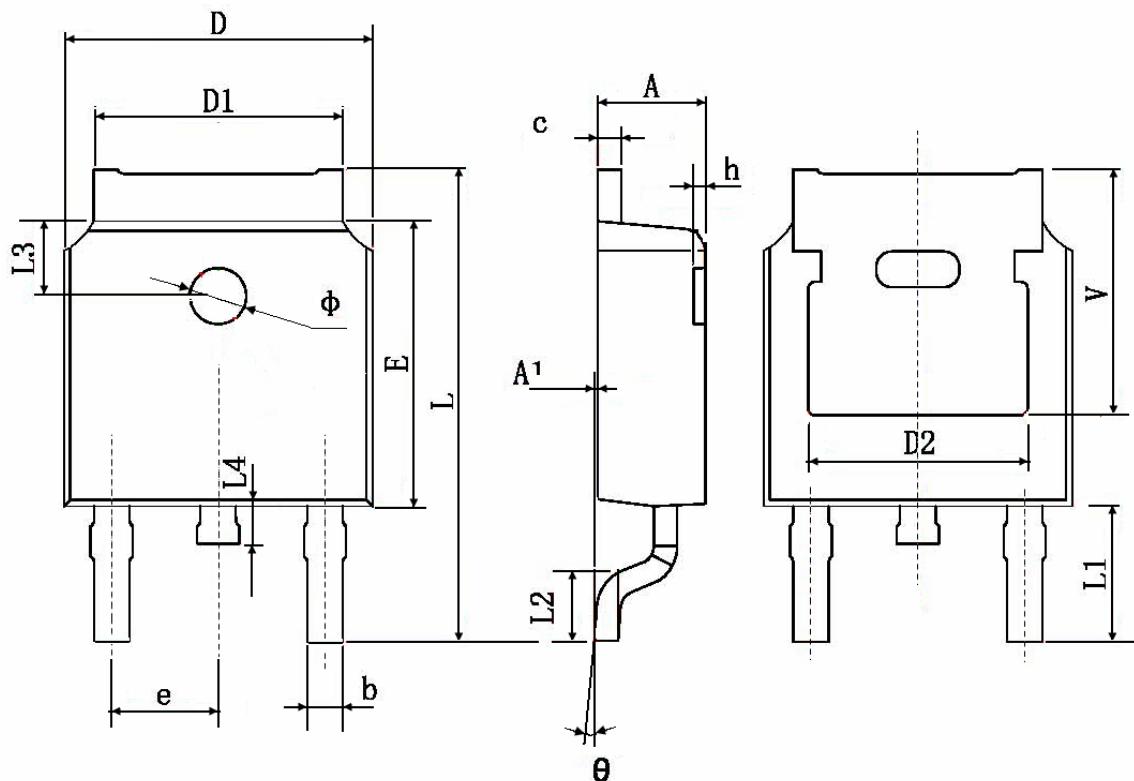
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Package Information:TO-252-3L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	